



US00D939459S

(12) **United States Design Patent** (10) **Patent No.:** **US D939,459 S**
Shimada et al. (45) **Date of Patent:** **** Dec. 28, 2021**

(54) **BOAT FOR WAFER PROCESSING APPARATUS**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; D15/144, 144.1, 199;
118/715, 500, 728, 729; 211/41.18;
(Continued)

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(57) **CLAIM**

The ornamental design for a boat for wafer processing apparatus, as shown and described.

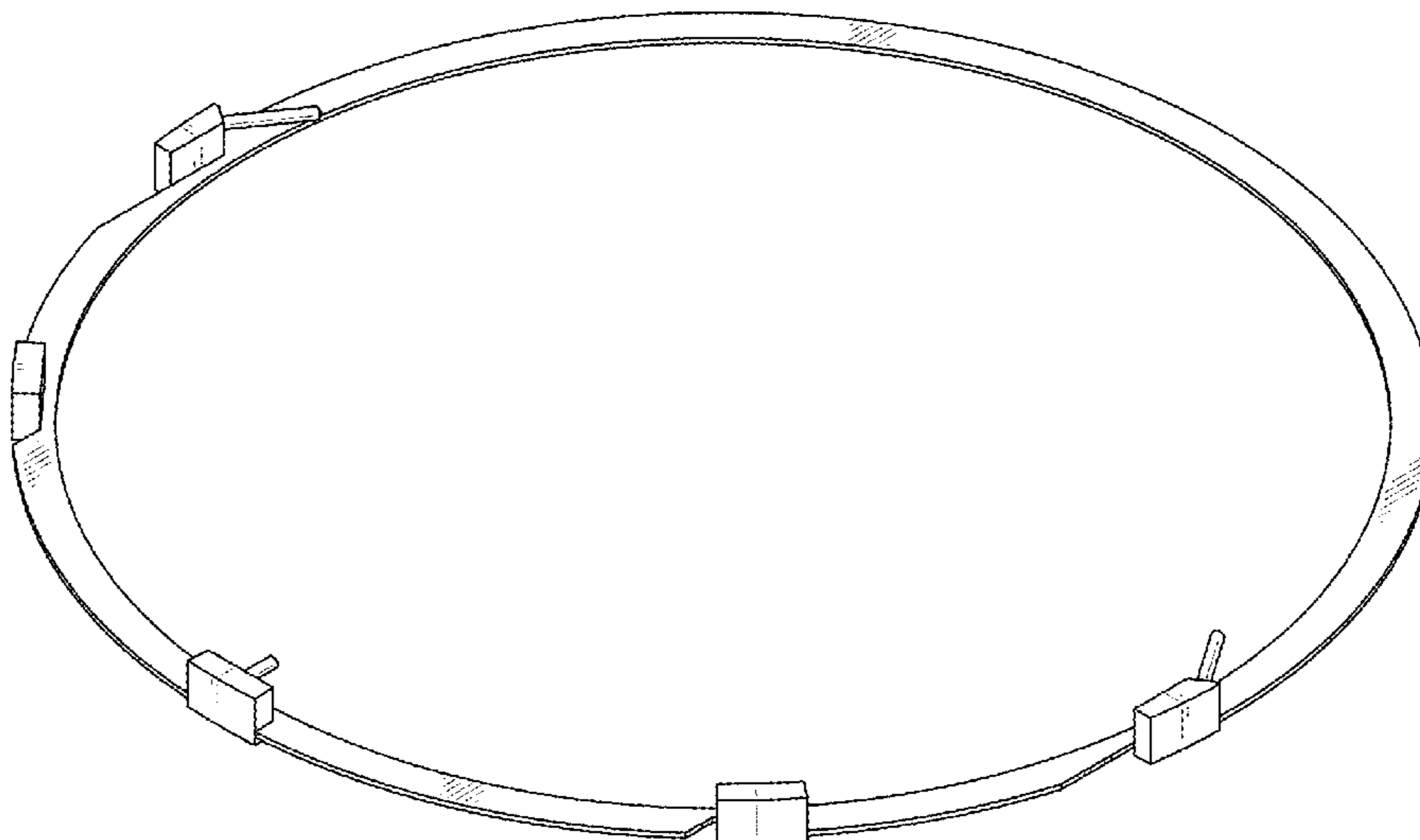
DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a boat for wafer processing apparatus showing our new design; FIG. 2 is a front elevational view thereof; FIG. 3 is a right side elevational view thereof; FIG. 4 is a left side elevational view thereof; FIG. 5 is a rear elevational view thereof; FIG. 6 is a top plan view thereof; FIG. 7 is a bottom plan view thereof; FIG. 8 is an enlarged portion view taken from the portion labeled FIG. 8 in FIG. 2; FIG. 9 is a cross-sectional view in the direction of the arrows along line 9-9 in FIG. 2; FIG. 10 is a cross-sectional view in the direction of the arrows along line 10-10 in FIG. 2; FIG. 11 is a perspective view of FIG. 8 with the cylindrical device shown in broken lines removed for ease of illustration; FIG. 12 is a front elevational view of FIG. 11; FIG. 13 is a right side elevational view of FIG. 11; FIG. 14 is a left side elevational view of FIG. 11; FIG. 15 is a rear elevational view of FIG. 11; FIG. 16 is a top plan view of FIG. 11; and, FIG. 17 is a bottom plan view of FIG. 11.

For clarity, due to the nature and size of the portions of the article that form no part of the claimed design in FIGS. 9 and 10, hatching to indicate the cut sections is not shown in FIGS. 9 and 10.

The dashed-dot-dashed lines represent the boundary lines of the claimed design in FIGS. 1-5 and 8. The even dashed broken lines showing a full or portions of a cylindrical device in FIGS. 1-10 are included for the purpose of illustrating environment and form no part of the claimed design. The dot-dash broken line of the box showing the enlarged portion view of FIG. 8 in FIG.2 shows the bounds of the enlarged portion view and forms no part of the claimed design.

1 Claim, 12 Drawing Sheets



(58) **Field of Classification Search**

USPC 432/253, 258; 156/345.51, 345.52,
156/345.53, 345.55; 414/217, 220.01,
414/935-941
CPC C23C 16/458; C23C 16/4581; C23C
16/4582; C23C 16/4583; C23C 16/4584;
C23C 16/4587; C23C 16/4588; H01L
21/673; H01L 21/67303; H01L 21/67306;
H01L 21/67309; H01L 21/67313; H01L
21/67316; H01L 21/67323; H01L
21/67326; H01L 21/6733; C30B 3/14

See application file for complete search history.

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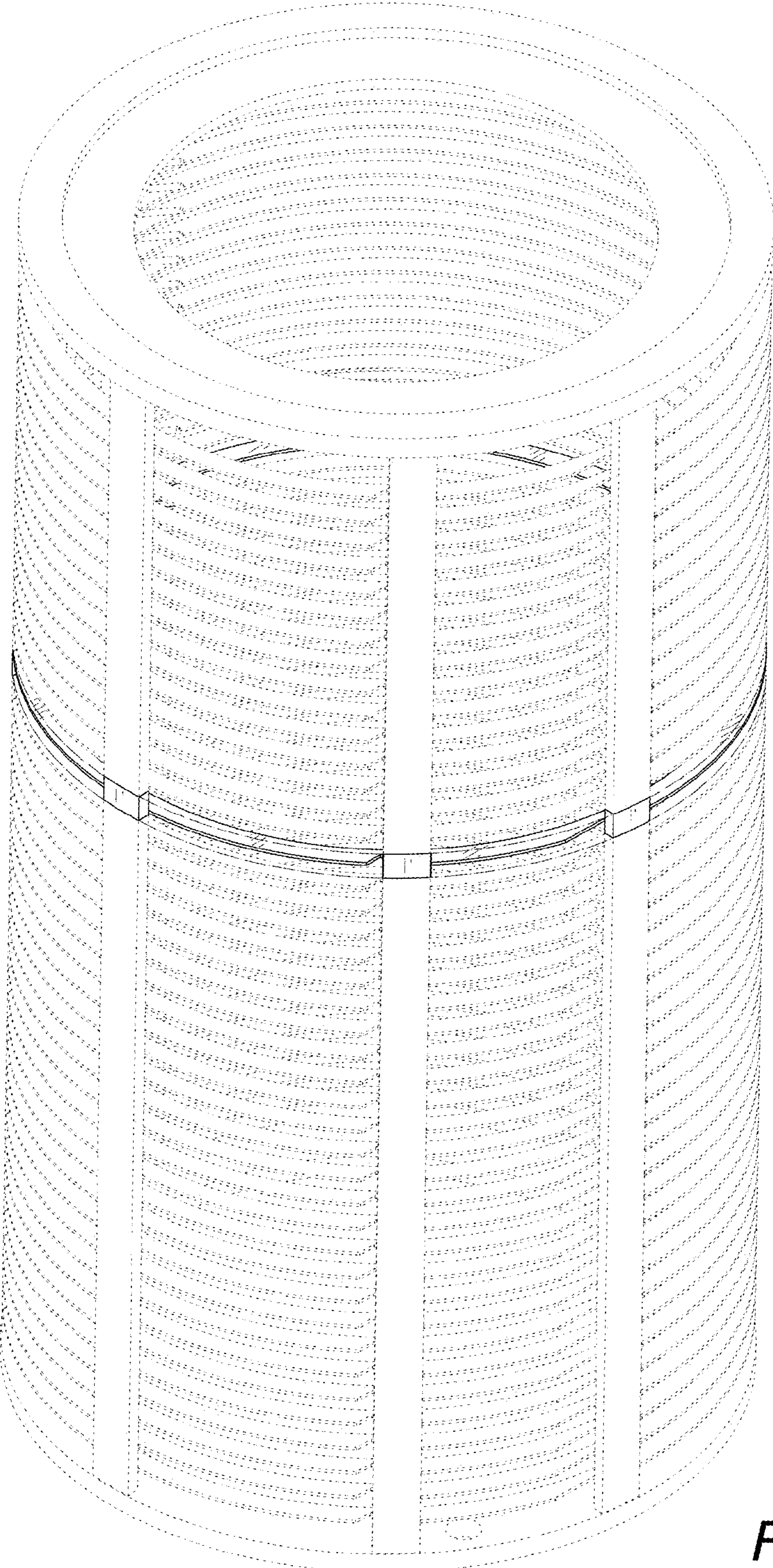


FIG. 1

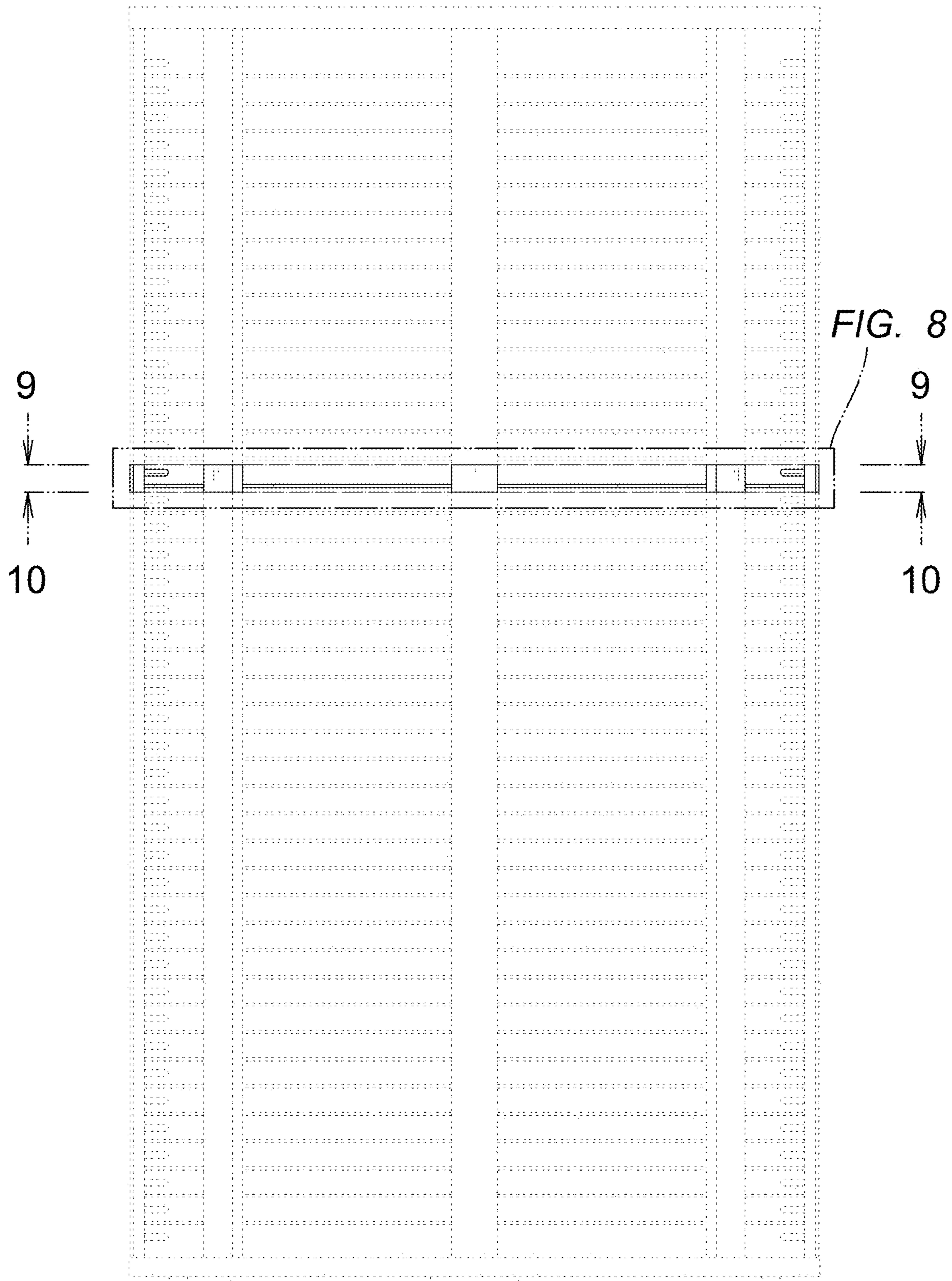


FIG. 2

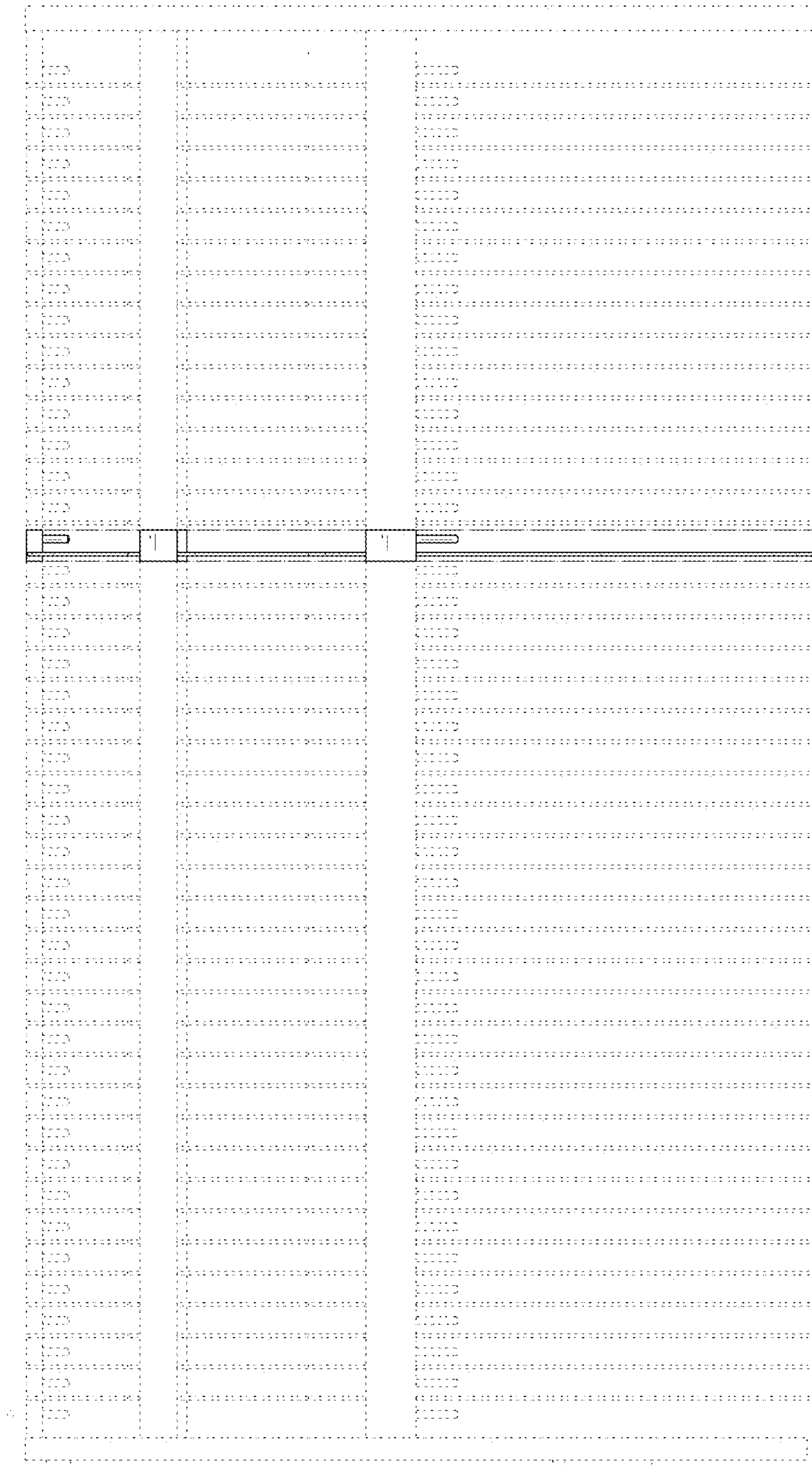


FIG. 3

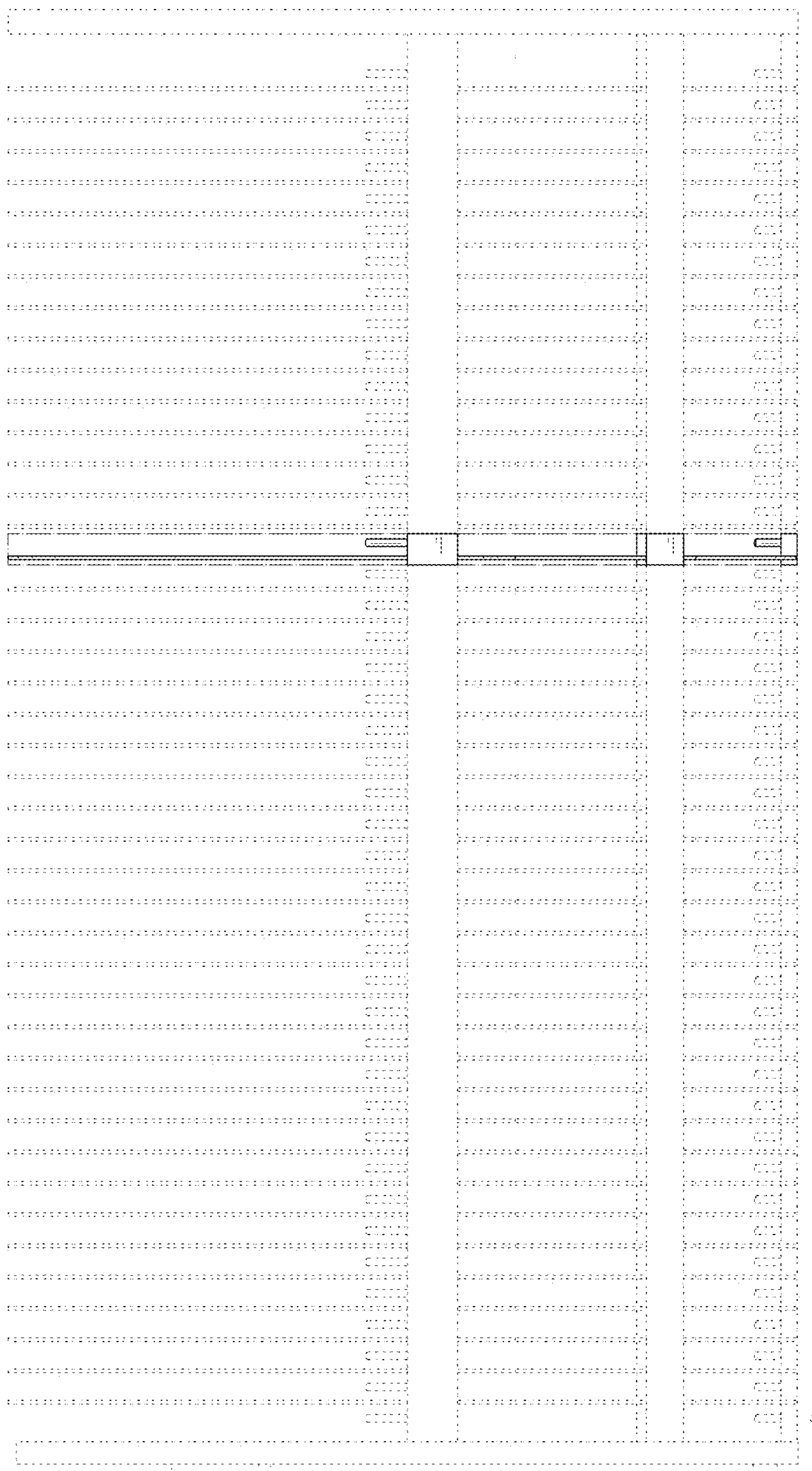


FIG. 4

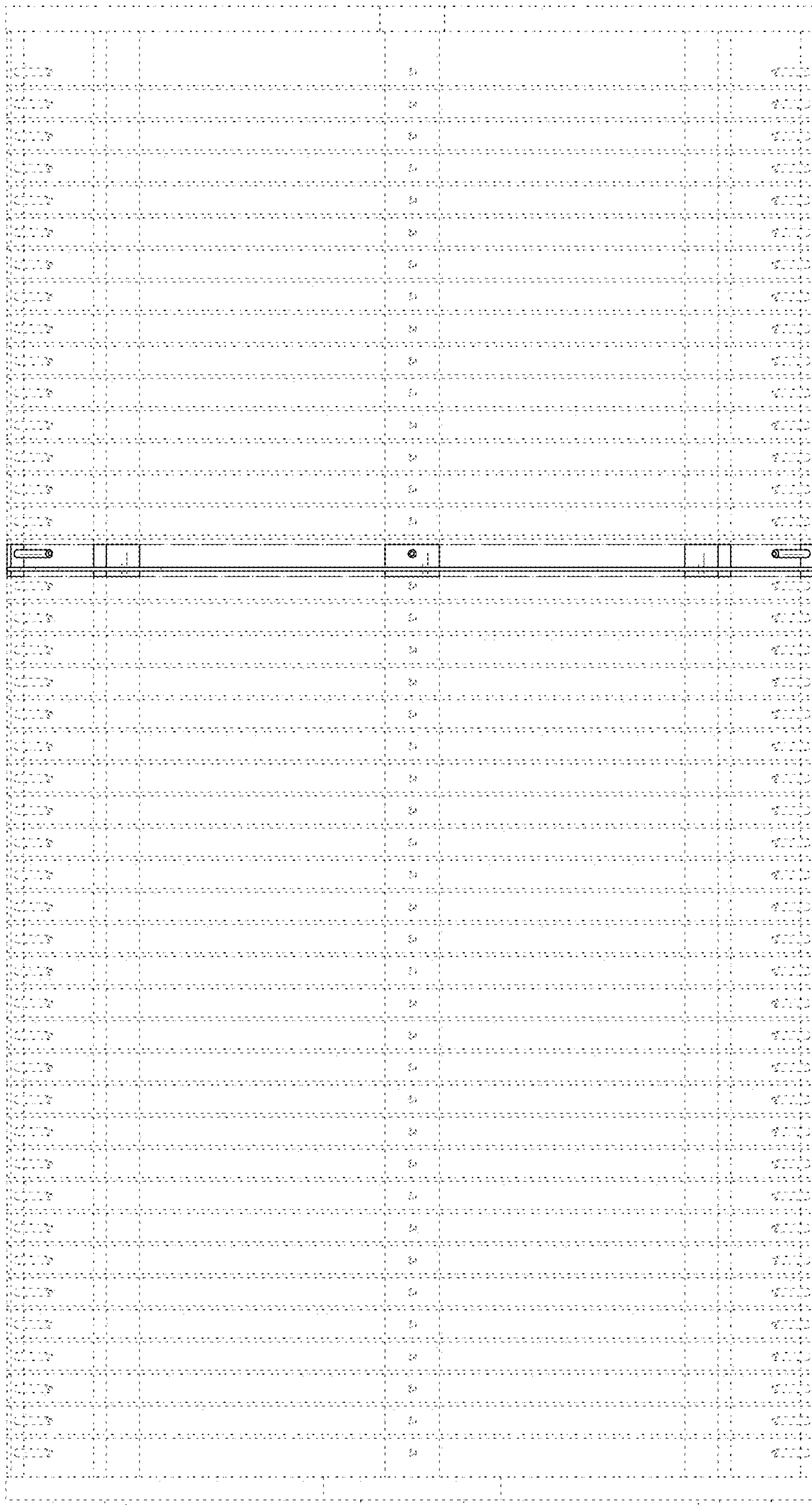


FIG. 5

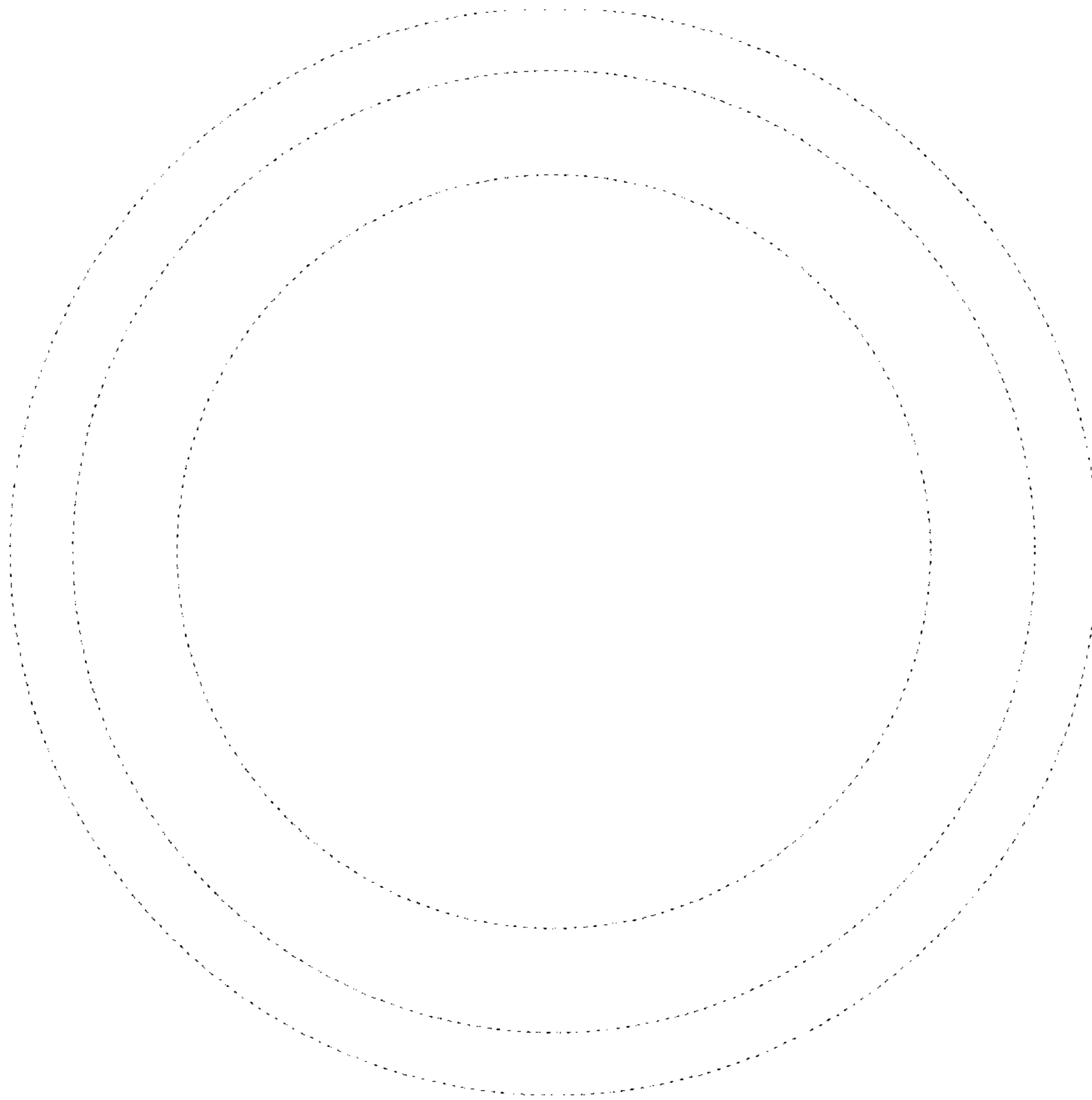


FIG. 6

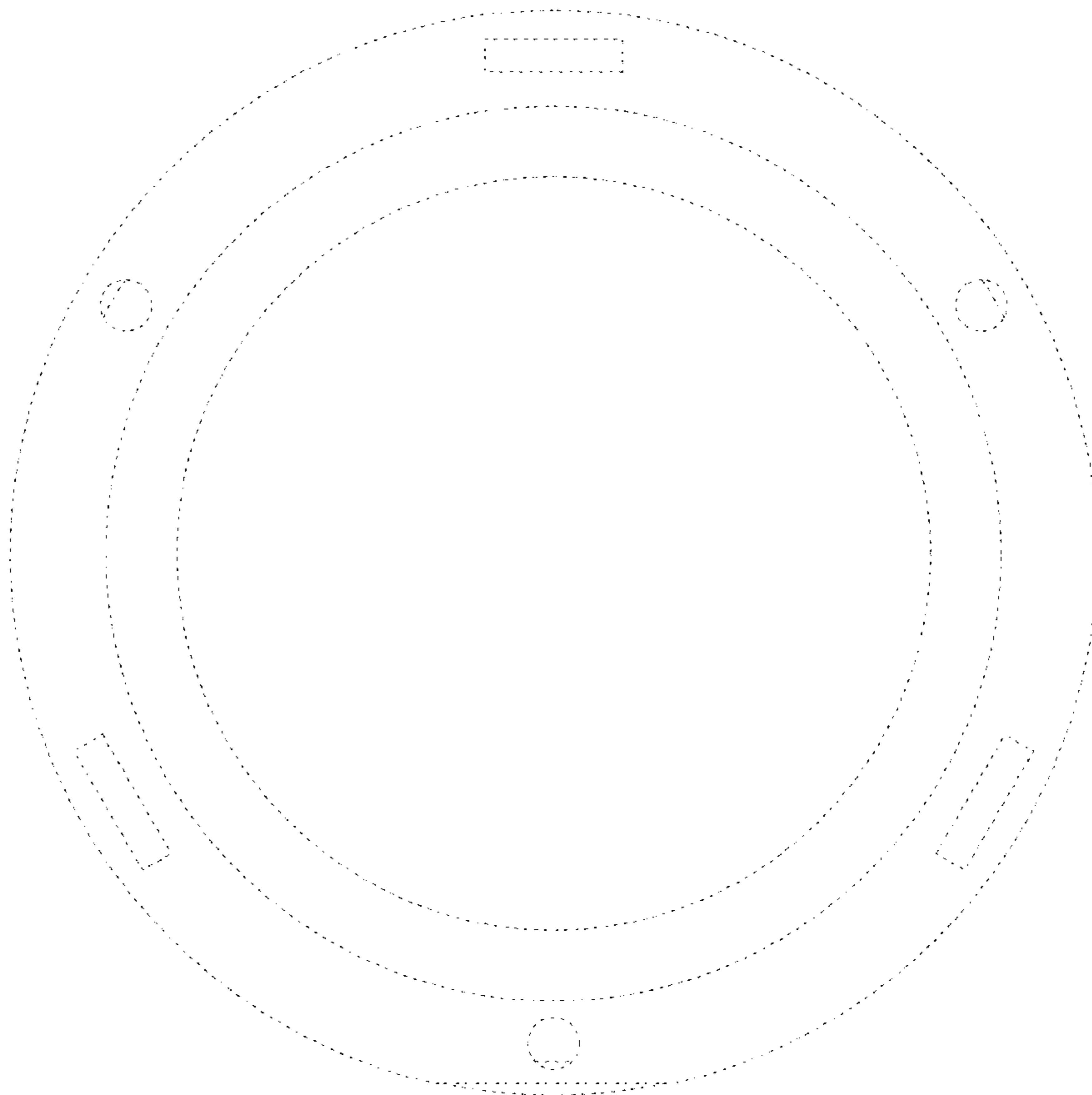


FIG. 7

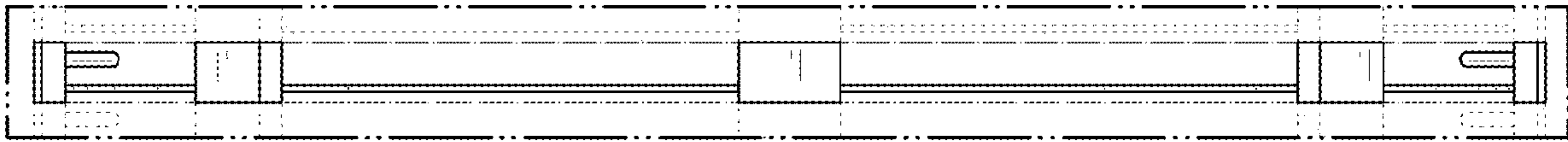


FIG. 8

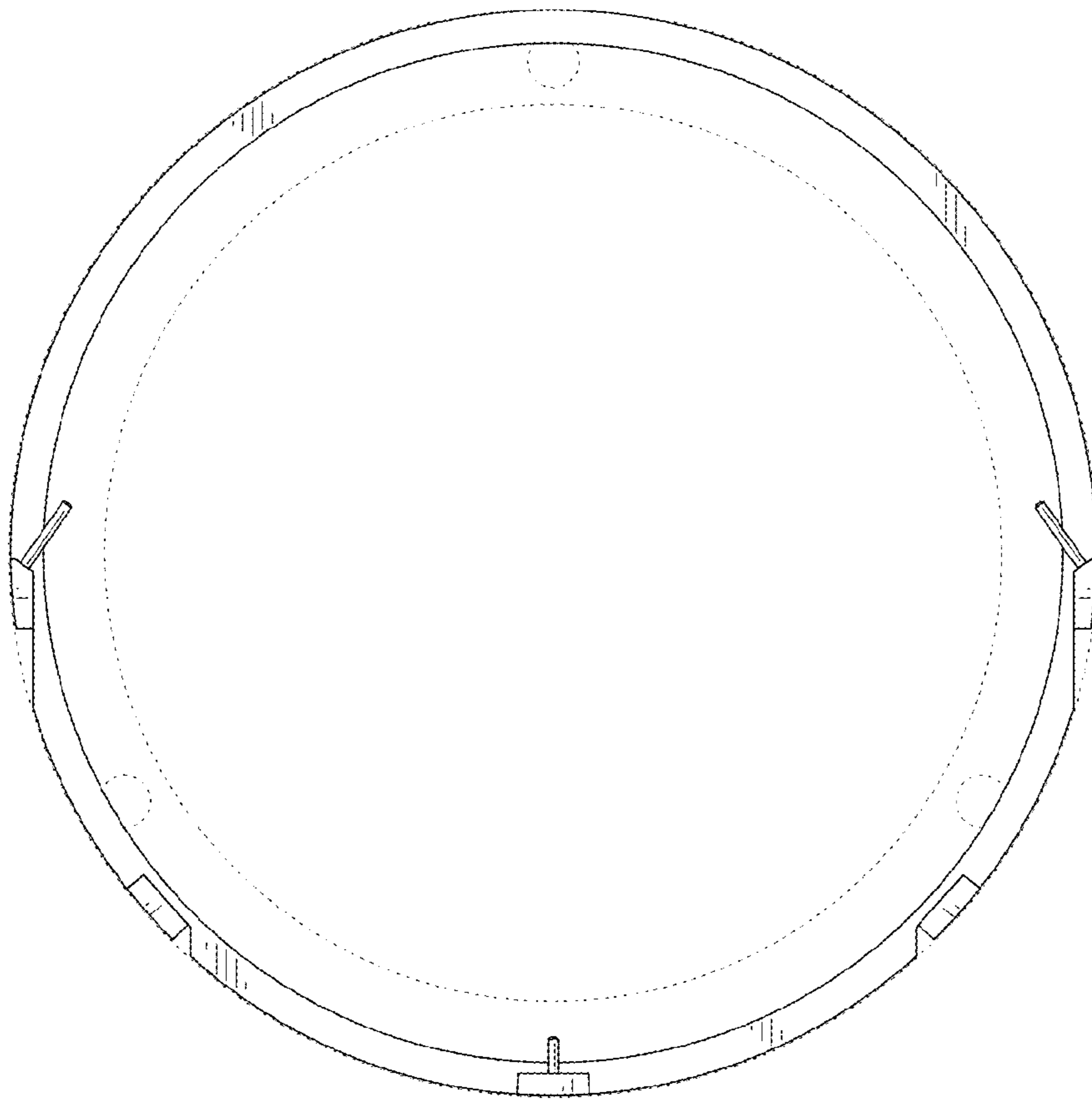


FIG. 9

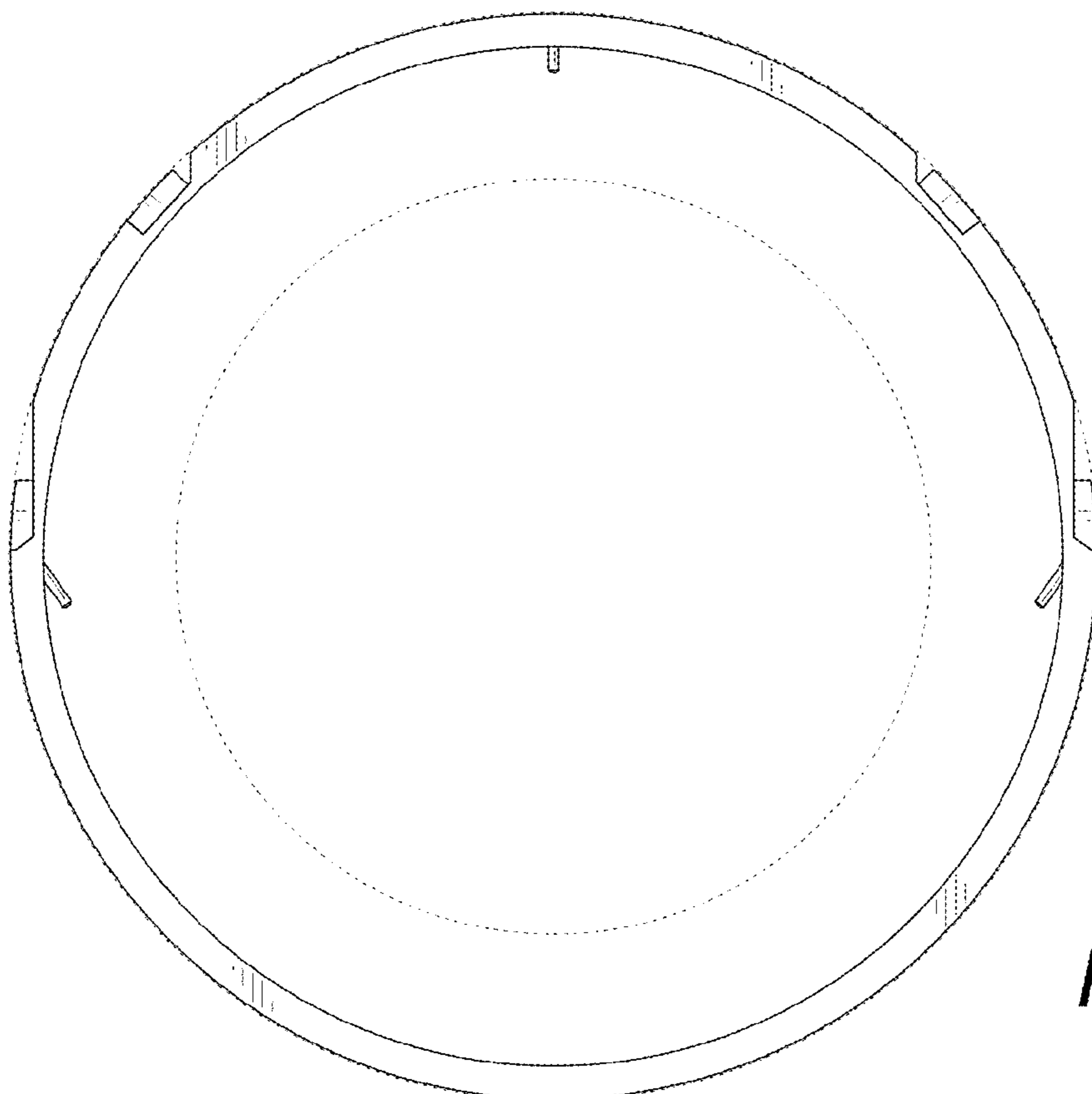


FIG. 10

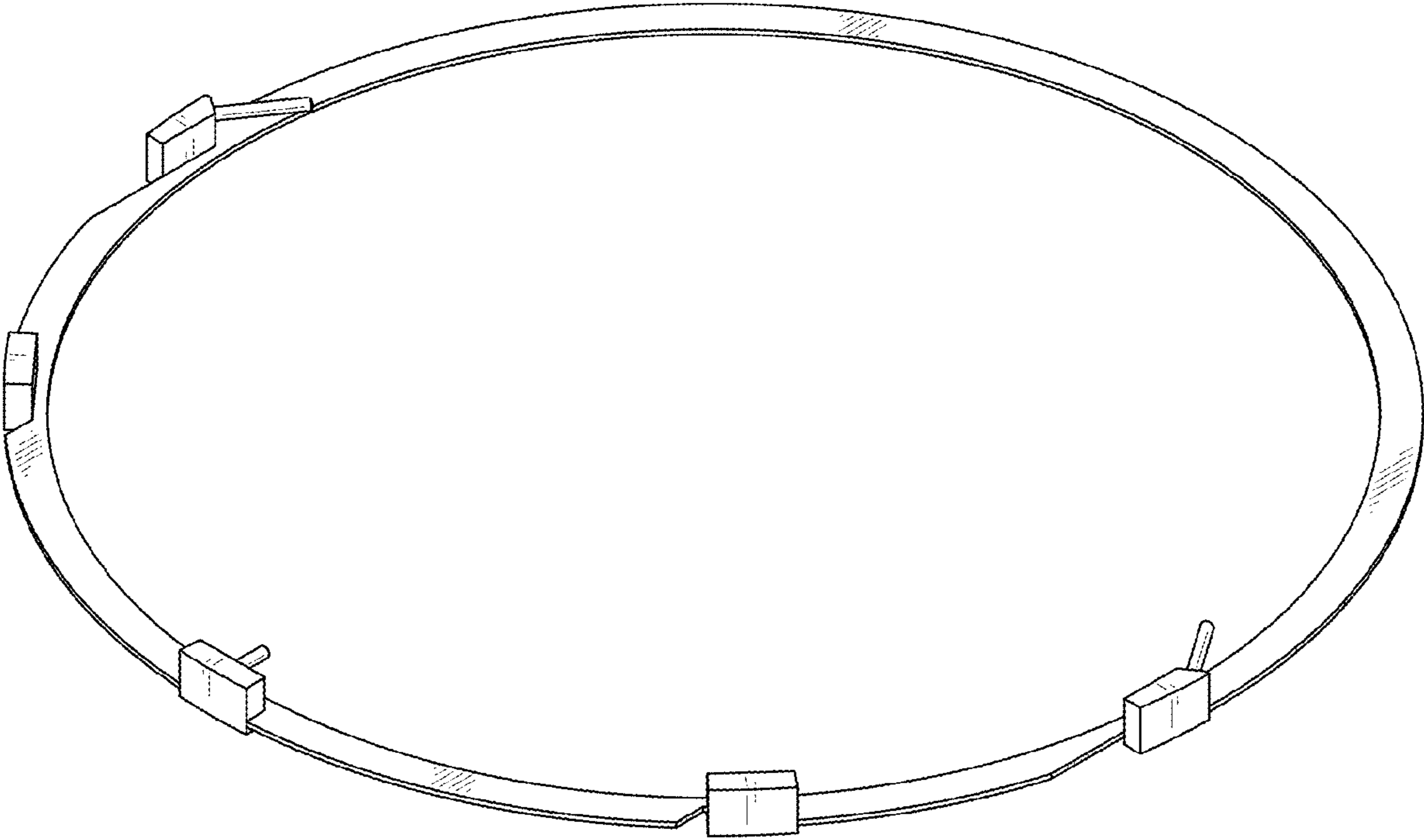


FIG. 11



FIG. 12

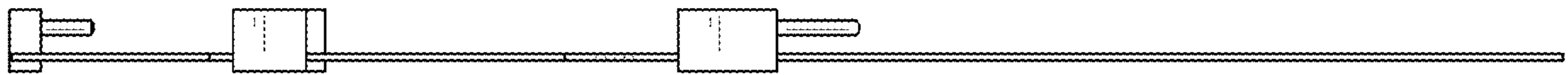


FIG. 13

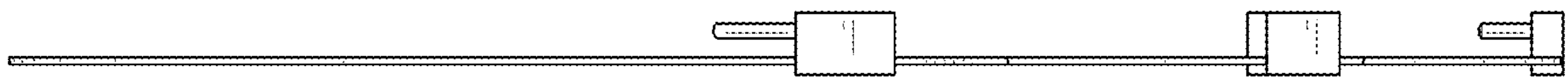


FIG. 14

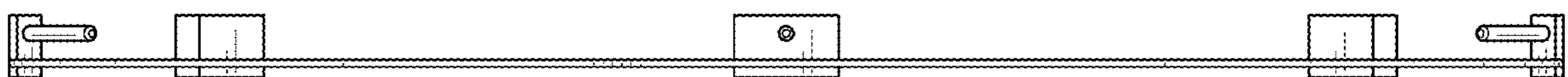


FIG. 15

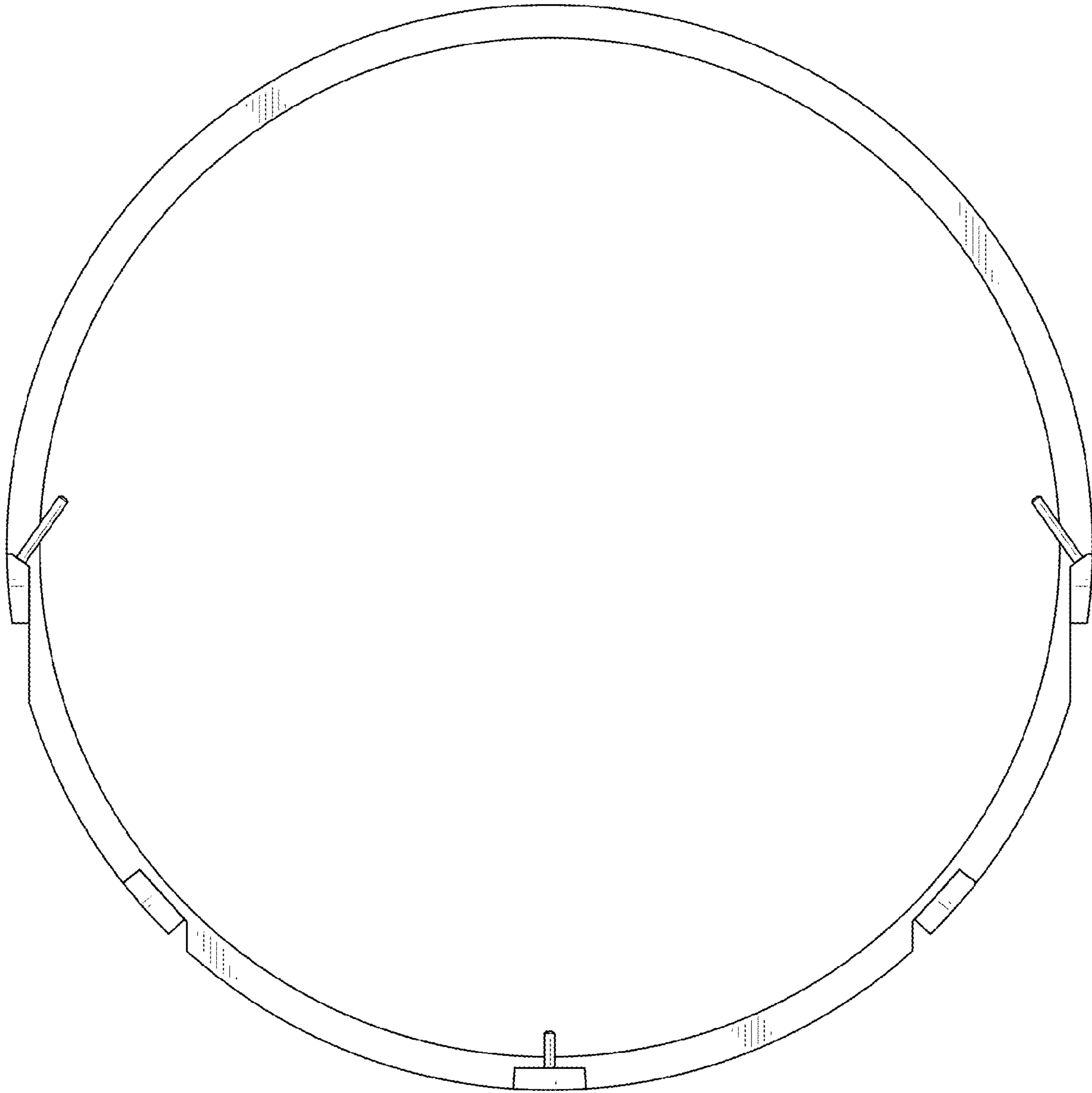


FIG. 16

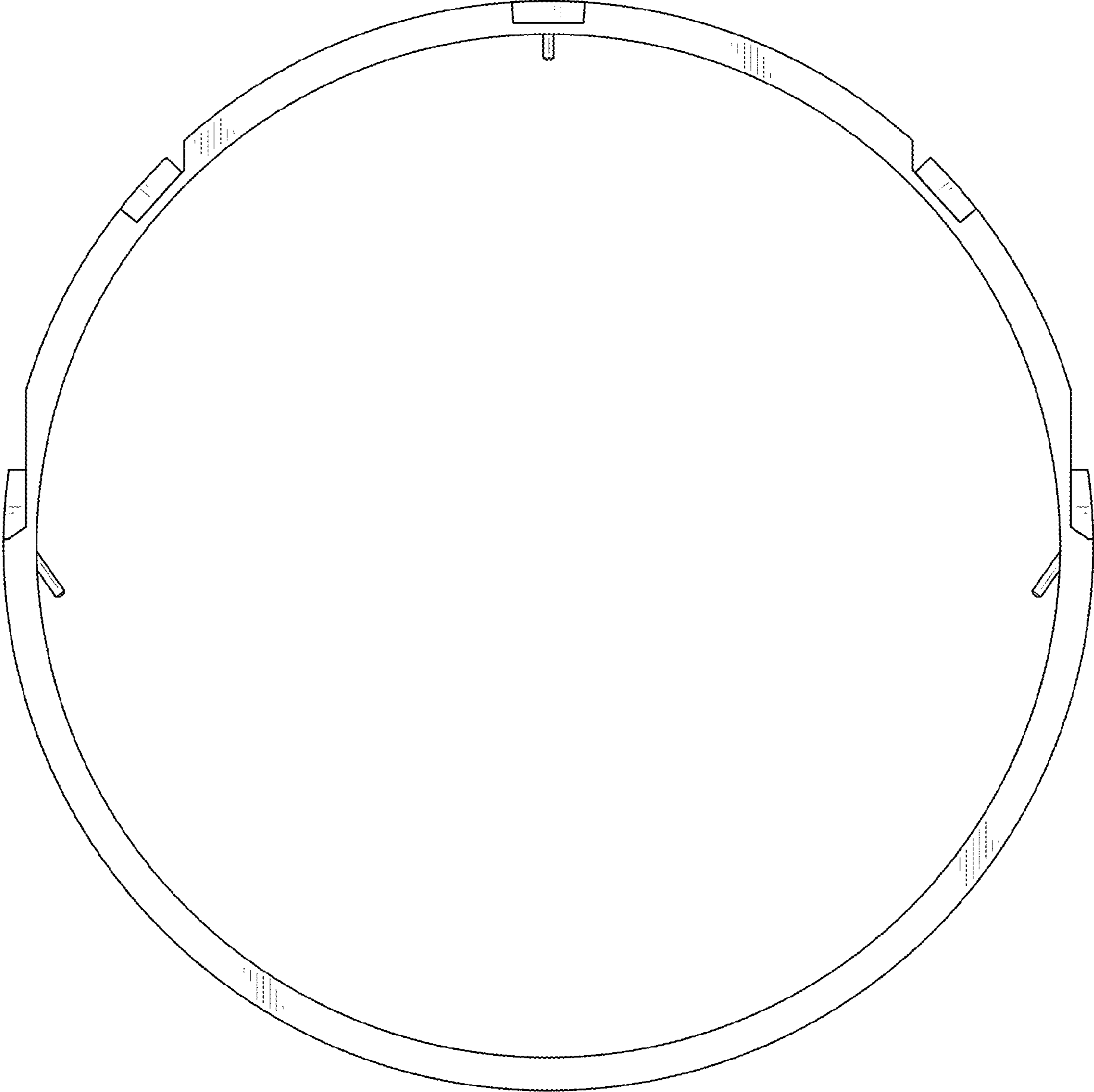


FIG. 17